# **3.3V Dual LVTTL/LVCMOS to Differential LVPECL Translator**

#### Description

The MC100LVELT22 is a dual LVTTL/LVCMOS to differential LVPECL translator. Because LVPECL (Low Voltage Positive ECL) levels are used, only +3.3 V and ground are required. The small outline 8-lead package and the low skew, dual gate design of the LVELT22 makes it ideal for applications which require the translation of a clock and a data signal.

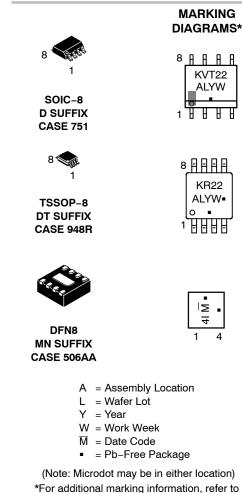
#### Features

- 350 ps Typical Propagation Delay
- <100 ps Output-to-Output Skew
- Flow Through Pinouts
- The 100 Series Contains Temperature Compensation
- LVPECL Operating Range: V<sub>CC</sub> = 3.0 V to 3.8 V with GND = 0 V
- When Unused TTL Input is left Open, Q Output will Default High
- Pb–Free Packages are Available



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Por additional marking information, refe Application Note AND8002/D.

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

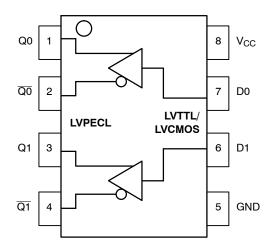


Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

EΡ

### Table 2. ATTRIBUTES

Charac	cteristics	Value
Internal Input Pulldown Resisto	N/A	
Internal Input Pullup Resistor		N/A
ESD Protection	Human Body Model Machine Model	> 4 kV > 200 V
Moisture Sensitivity, Indefinite T	ime Out of Drypack (Note 1)	Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count	164	
Meets or exceeds JEDEC Spec	EIA/JESD78 IC Latchup Test	

1. For additional information, see Application Note AND8003/D.

#### Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	Positive Power Supply	GND = 0 V		7	V
VI	Input Voltage	GND = 0 V	$V_{I}\!\leq\!V_{CC}$	7	V
l <sub>out</sub>	Output Current	Continuous Surge		50 100	mA mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SO-8 SO-8	190 130	°C/W °C/W
$\theta_{\text{JC}}$	Thermal Resistance (Junction-to-Case)	std bd	SO-8	41 to 44 ± 5%	°C/W
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W °C/W
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	std bd	TSSOP-8	41 to 44 ± 5%	°C/W
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T <sub>sol</sub>	Wave Solder Pb Pb-Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	(Note 2)	DFN8	35 to 40	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

2. JEDEC standard multilayer board - 2S2P (2 signal, 2 power)

#### Table 1. PIN DESCRIPTION

PIN	FUNCTION
Qn, <u>Qn</u> D0, D1 V <sub>CC</sub> GND	LVPECL Differential Outputs LVTTL/LVCMOS Inputs Positive Supply Ground
EP	(DFN8 only) Thermal exposed pad must be connected to a suf- ficient thermal conduit. Electric- ally connect to the most negative supply (GND) or leave uncon- nected, floating open.

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I <sub>CC</sub>	Power Supply Current			28			28			29	mA
V <sub>OH</sub>	Output HIGH Voltage (Note 4)	2275		2420	2275		2420	2275		2420	mV
V <sub>OL</sub>	Output LOW Voltage (Note 4)	1490		1680	1490		1680	1490		1680	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

3. Output parameters vary 1:1 with  $V_{CC}$ .  $V_{CC}$  can vary  $\pm 0.15$  V. 4. Outputs are terminated through a 50 ohm resistor to  $V_{CC}$ -2 volts.

#### Table 5. LVTTL/LVCMOS INPUT DC CHARACTERISTICS $V_{CC}$ = 3.3 V; T<sub>A</sub> = -40°C to 85°C (Note 5)

Symbol	Characteristic	Min	Тур	Max	Unit	Condition
I <sub>IH</sub>	Input HIGH Current			20	μA	V <sub>IN</sub> = 2.7 V
I <sub>IHH</sub>	Input HIGH Current			100	μA	V <sub>IN</sub> = V <sub>CC</sub>
IIL	Input LOW Current			-0.2	mA	V <sub>IN</sub> = 0.5 V
V <sub>IK</sub>				-1.2	V	I <sub>IN</sub> = -18 mA
VIH	Input HIGH Voltage	2.0			V	
VIL	Input LOW Voltage			0.8	V	

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5.  $V_{CC}$  can vary ±0.15 V.

#### Table 6. AC CHARACTERISTICS V<sub>CC</sub> = 3.3 V; GND = 0.0 V (Note 6)

			<b>−40°C</b>			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f <sub>max</sub>	Maximum Toggle Frequency					350					MHz
<sup>t</sup> PLH	Propagation Delay (Note 7)	200	350	600	200	350	600	200	350	600	ps
<sup>t</sup> skew	Skew Output-to-Output Part-to-Part		30	100 400		30	100 400		30	100 400	ps
tJITTER	Random Clock Jitter (RMS)					1.6					ps
t /t r f	Output Rise/Fall Time (20-80%)	200		550	200		500	200		500	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

6.  $V_{CC}$  can vary  $\pm 0.15$  V.

7. Specifications for standard TTL input signal.

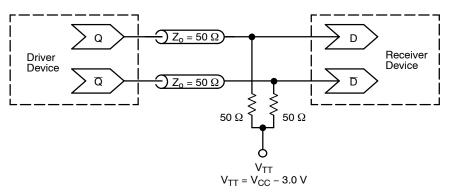


Figure 1. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>	
MC100LVELT22D	SOIC-8	98 Units / Rail	
MC100LVELT22DG	SOIC-8 (Pb-Free)	98 Units / Rail	
MC100LVELT22DR2	SOIC-8	2500 / Tape & Reel	
MC100LVELT22DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel	
MC100LVELT22DT	TSSOP-8	100 Units / Rail	
MC100LVELT22DTG	TSSOP-8 (Pb-Free)	100 Units / Rail	
MC100LVELT22DTR2	TSSOP-8	2500 / Tape & Reel	
MC100LVELT22DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel	
MC100LVELT22MNR4	DFN8	1000 / Tape & Reel	
MC100LVELT22MNRG	DFN8 (Pb-Free)	1000 / Tape & Reel	

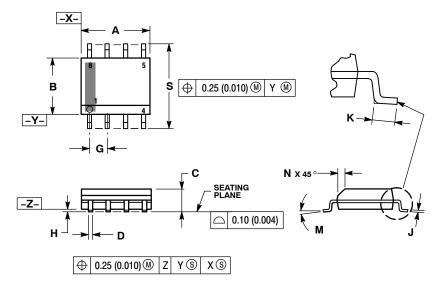
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **Resource Reference of Application Notes**

AN1405/D	-	ECL Clock Distribution Techniques
AN1406/D	_	Designing with PECL (ECL at +5.0 V)
AN1503/D	_	ECLinPS <sup>™</sup> I/O SPiCE Modeling Kit
AN1504/D	_	Metastability and the ECLinPS Family
AN1568/D	-	Interfacing Between LVDS and ECL
AN1672/D	-	The ECL Translator Guide
AND8001/D	_	Odd Number Counters Design
AND8002/D	_	Marking and Date Codes
AND8020/D	-	Termination of ECL Logic Devices
AND8066/D	-	Interfacing with ECLinPS
AND8090/D	-	AC Characteristics of ECL Devices

#### PACKAGE DIMENSIONS

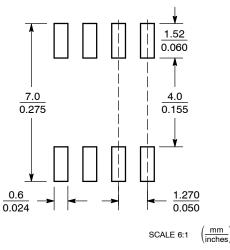
SOIC-8 NB CASE 751-07 **ISSUE AH** 

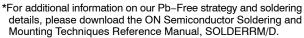


- NOTES: 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER. 2. З.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. 4.
- PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07. 5.
- 6.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.050 BSC		
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
κ	0.40	1.27	0.016	0.050	
М	0 °	8 °	0 °	8 °	
Ν	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

#### SOLDERING FOOTPRINT\*

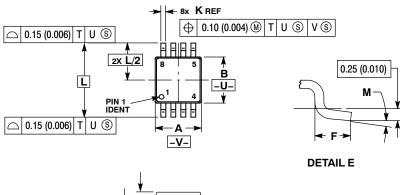




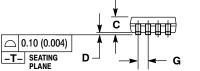
#### PACKAGE DIMENSIONS

#### TSSOP-8 DT SUFFIX PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**

DETAIL E



G





-W-

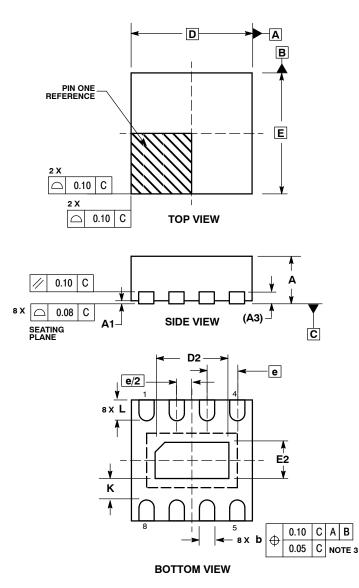
- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- DIMENSIONED AND FOLLINATION FOR TAKIN Y14.5M, 1982.
  CONTROLLING DIMENSION: MILLIMETER.
  DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65	BSC	0.026	BSC
K	0.25	0.40	0.010	0.016
L	4.90	BSC	0.193	BSC
Μ	0°	6 °	0°	6°



#### PACKAGE DIMENSIONS

DFN8 CASE 506AA-01 ISSUE D



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M. 1994.
- ASME Y14.3M, 1994.
  CONTROLLING DIMENSION: MILLIMETERS.
  DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
  COPLANARITY APPLIES TO THE EXPOSED DADA SWITL AS THE TERMINAL.
- PAD AS WELL AS THE TERMINALS.

	MILLIMETERS					
DIM	MIN	MAX				
Α	0.80	1.00				
A1	0.00	0.05				
A3	0.20	REF				
b	0.20	0.30				
D	2.00	BSC				
D2	1.10	1.30				
E	2.00	BSC				
E2	0.70	0.90				
е	0.50	BSC				
K	0.20					
L	0.25	0.35				

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